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CSI-427 VLSI design and Analysis

1.A

Am Standard Cell Based Design:- A Standard Cell based design requires development of full custom mask yet. the Standard Cell is also known as the PolyCell. In this approach all of the commonly used logic cells are developed characterized and stored in a standard cell library.

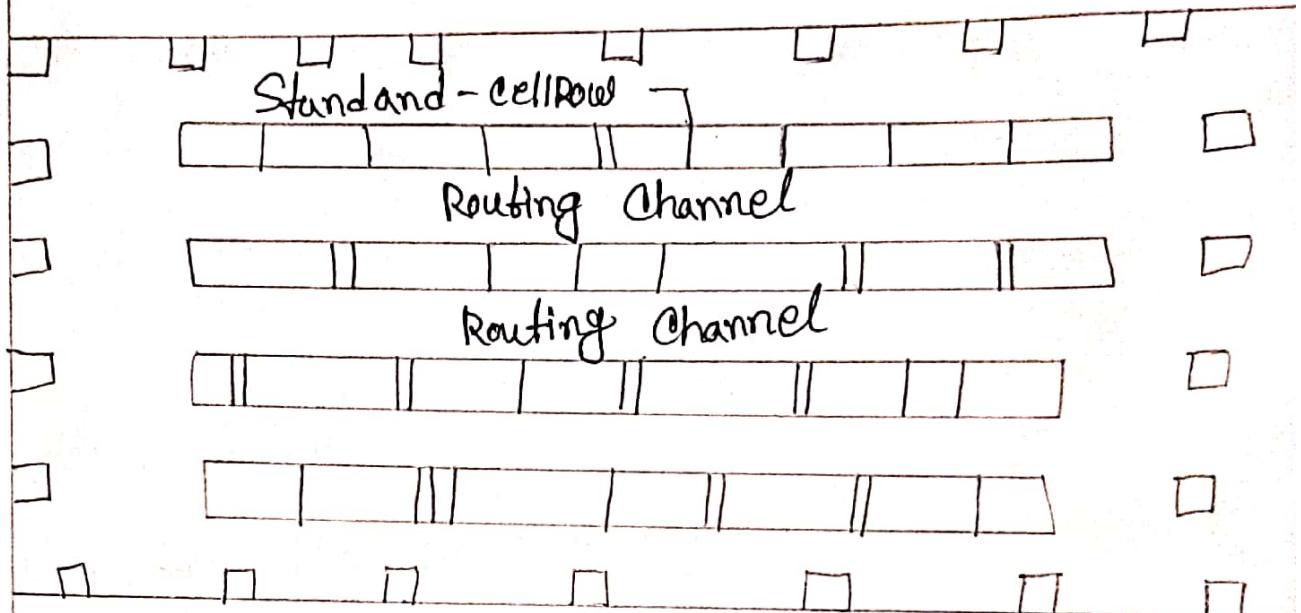
A library may contain of few hundred cells including inverters, NAND, NOR, complex AND, OR gates D-latches and flip-flops. Each gate type can be implemented in several versions to provide adequate driving capability for different to from the

inverter gate can have standard size

double and quadruple size so that the chip

designer can select the proper size to obtain high circuit speed and layout.

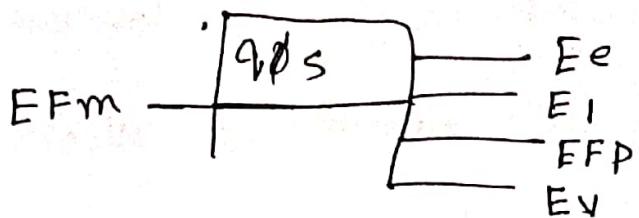
P-2
density. Each cell has according to several different categories such as.



figuis:- Floor plan Standard cell based design

- ① Delay time versus load capacitance.
- ② circuit simulation model.
- ③ Timing simulation model.
- ④ fault simulation model.
- ⑤ cell data for place-and-route.
- ⑥ mas R data.
- ⑦ Automated placement of the cell and routing.

P.-04 A voltage called electromotive force is quantitative expression of the potential differences Change between two Points



ϕ_s = Surface

Consider the Cross sectional view of channel

$$V_s = V_B = 0 \text{ to } E_{pm} = Q_{ms} - E_{fp}$$

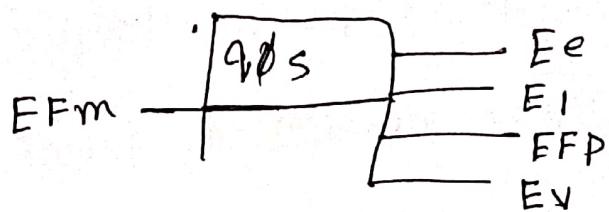
$$V_c = (y=0) = V_s \text{ (and } V_c (y=2))$$

the spatial geometry equation made

indicate

$$dn = \frac{dy}{Q_{msy}} \times 10^{-7} \text{ cm}$$

P.-oii A voltage called electromotive force is quantitative expression of the potential differences charge between two points



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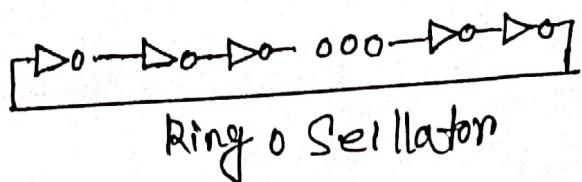
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$$dn = \frac{dy}{q_{ms}y} \times 10^{-7} \text{ cm}$$

~~Q=AT~~
~~2-0A~~

Oscillation Solutions:-



Ring Oscillator

The logical effort of the inverter is $g = 1$ by definition. The electrical effort of each inverter is also 1 because it drives single identical load. The parasitic delay is also 1.

The delay of each stage is

$$\begin{aligned} d &= g_b + P \\ &= 1 \times 1 + 1 \\ &= 2 \end{aligned}$$

An N-stage ring oscillator has a period of $2N$ stage delays because a pulse must propagate twice around the ring ring to regain the original polarity.

P.T.O

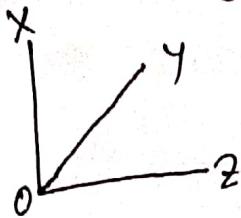
Therefore the period is $T = 2 \times 2N$ The frequency
is the of the period $1/4n$

A 31 - stage ring oscillator in a 65nm process
has a frequency $1/(4 \times 31 \times 3) = 2.7 \text{ GHz}$

Note that ring oscillators are often used
as process monitors to judge if a particular
chip is faster or slower than nominally ex-
pected one the inverters should be
replaced with the nominal replaced with
NAND gate to turn the ring.

2B

Ans: Linear delay model Inv 2:-



This post talks about logical effort and parasitic delay in linear delay model in VLSI. Parasitic delay in linear delay model depends on the sum of the gate normalized delay expressed as the sum of parasitic delay P and effort delay $f = P + f$. The effort delay depends on the fan-out n of the gate $f = gn$ where g is a logical effort what's fan-out or electrical effort was driving one in identical way.

p-08

- ④ In general the propagation delay of a gate can be written as $T_p = f + P$

P is the delay due to intrinsic capacitance
 f is the effort delay or stage effort
and depends on the complexity and fanout of the gate.

- ④ The stage effort is $f = gh$ with the Complexity represented by the logical

- ④ An inverter is defined to have a logical effort of 1.

- ④ A gate driving n identical copies of itself is said to have an electrical effort.

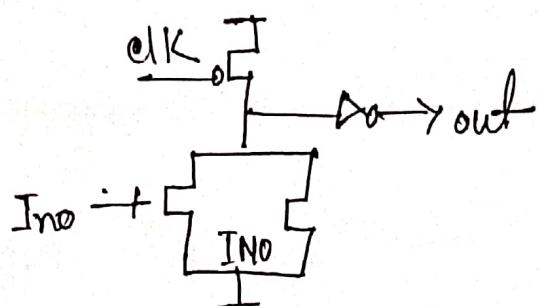
- ④ The electrical effort of non-identical copies of the gate on any type load to be $h = C_{out} / C_{in}$.

3.A

Domino nose douggets:- The rapid advantage

in VLSI design in Domino with block

Dingarve



Domino Cell.

During the precharge phase when the clock is low the precharging gets on and the dynamic node is connected to the VDD and gets precharged to VDD when clock goes high the evaluation phase starts and the output gets evaluated with the pull down network and conditionally the above proposed circuit has negative no.

- The Domino logic Stage consists of logic
realized using N-mos pull down
network. Pull up the work consists
of a single pre charge dynamic node
to logic high as shown. The dynamic node
is cascaded into stated noise inverters
and can be connected. The compensation
called keeper is used. In the first Domino
proposal the gate of the keeper is
connected to the ground.

4.A

Source of Power Dissipation: The power dissipation in CMOS Circuits comes from two components.

- ① Dynamic dissipation.
- ② Static dissipation.

Dynamic: ① due to charging and discharging load capacitance as gate switch.

② Short circuit while to the form of leakage current when the system is not powered on is in standby mode.

In Circuits there are several sources of leakage current including subthreshold leakage, drain leakage, gate leakage etc.

Leakage current includes drain current around transistors and n-wells tunnel current, gate leakage etc. It increases in reverse effect the dynamic power.

Static Power:- when a mos circuit is in an idle state there is still some static power dissipation. In a silicon chip there are millions of transistors and the current is comparable to leakage and sub-threshold currents depend upon processing parameters.

$$F_{\text{reverse}} = A \cdot J_S (eK^T_2)$$

A is the tunneling area.

ϕ is the charge of electron

K is operating temperature.

Diode formation due to mos structure is inherent in increase in temperature millions of transistors to the static power dissipation.